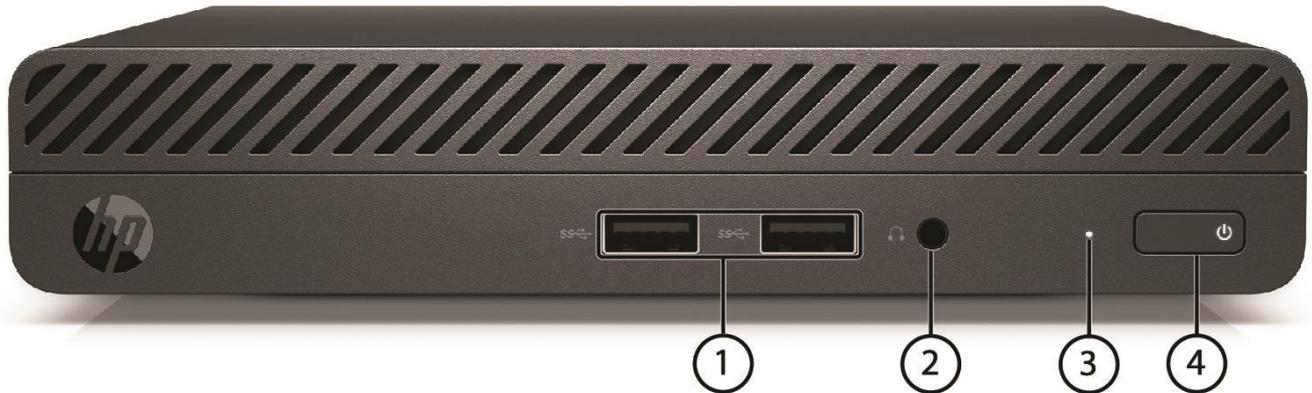


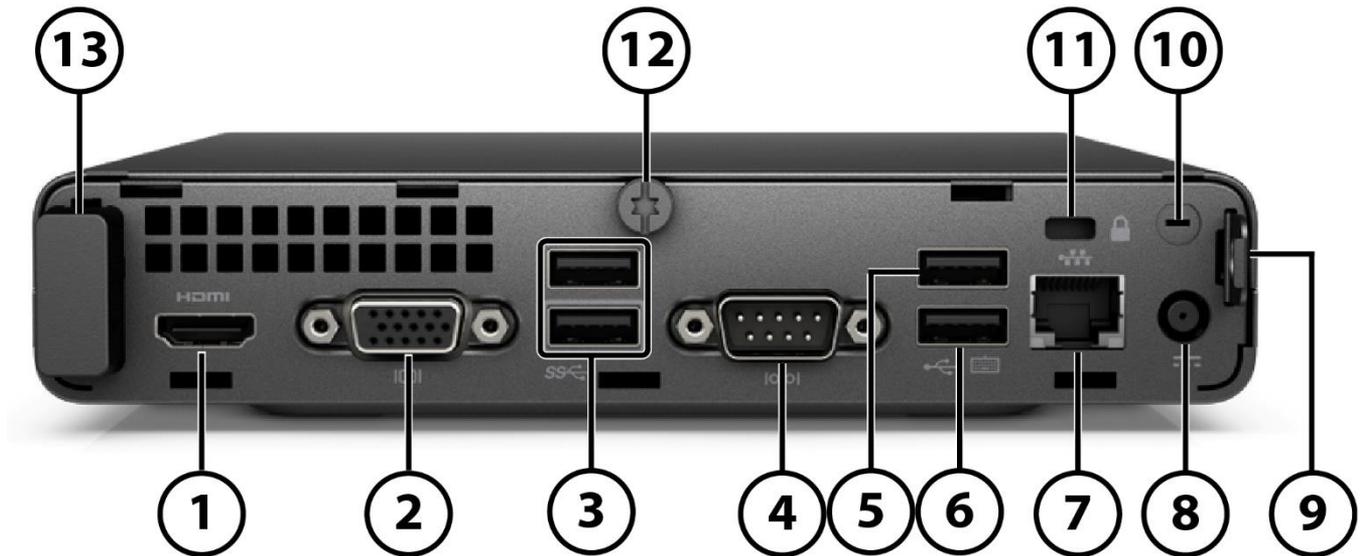
HP 260 G3 Desktop Mini Business PC



Front

1. (2) USB 3.1 Gen 1 (5 Gbits/s data speed)
2. Combo Microphone/Headphone Jack
3. Hard drive activity light
4. Dual-state power button

Overview



Back

- | | |
|---|--|
| 1. HDMI 1.4 | 7. RJ45 network connector |
| 2. VGA | 8. Power connector |
| 3. (2) USB 3.1 Gen 1 ports (5 Gbits/s data speed) | 9. Padlock loop |
| 4. Serial port | 10. External WLAN antenna opening ¹ |
| 5. (1) USB 2.0 ports | 11. Standard lock slot (10 mm) |
| 6. (1) USB 2.0 ports (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS) | 12. Cover release thumbscrew |
| | 13. Internal WLAN antenna cover |

1. Must be configured at time of purchase

Overview

AT A GLANCE

- 7th Generation Intel® processors (up to Core™ i5)¹, featuring integrated Intel® HD Graphics
- Choice of Windows 10 Home, Windows 10 Professional, and FreeDOS 2.0
- Up to 32GB of DDR4 Synchronous Dynamic Random Access Memory (SDRAM)
- Optional M.2 PCIe NVMe solid state drives (SSD) enabling faster system startup and application launches
- Support for up to two monitors via two standard HDMI 1.4 and VGA connectors
- Serial port support comes standard enabling support for legacy peripherals
- Integrated Realtek RTL8111HSH-CG Gigabit Network Connection
- Optional Wi-Fi 802.11ac connectivity
- Integrated HD audio featuring Conexant CX20632
- Trusted Platform Module (TPM) 2.0
- VESA mounting incorporated into chassis design
- Dust filter available for Desktop Mini
- High efficiency energy saving power supply
- ENERGY STAR® certified. EPEAT® 2019 registered where applicable. Registration may vary by country. See <http://www.epeat.net> for registration status by country³. Search keyword generator on HP's 3rd party option store for solar generator accessories at <http://www.hp.com/go/options>
- PC chassis and all internal components and modules are manufactured with low halogen content²
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support

1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance

2. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

3. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit <http://www.epeat.net> for more information.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Standard Features and Configurable Modules

OPERATING SYSTEMS

Preinstalled (Windows)

Windows® 10 Pro 64 ¹
Windows® 10 Pro 64 (National Academic License) ^{1,2}
Windows® 10 Home 64 ¹
Windows® 10 Home Single Language 64 ¹

Pre-installed (Other)

FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com/>
2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see <https://aka.ms/ProEducation> for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on <http://www.support.hp.com>

PROCESSOR

Intel® 7th Generation Core™ Processors

Intel® Core™ i5-7200U Processor¹
15W
2.5 GHz base frequency
Up to 3.1 GHz max. turbo frequency with Intel® Turbo Boost Technology²
3 MB cache, 2 cores, 4 threads
Intel® HD Graphics 620
Supports DDR4 memory up to 2133 MT/s data rate

Intel® Core™ i3-7130U Processor¹
15W
2.7 GHz base frequency
3 MB cache, 2 cores, 4 threads
Intel® HD Graphics 620
Supports DDR4 memory up to 2133 MT/s data rate

Intel® 7th Generation Pentium® Processors

Intel® Pentium® Gold 4415U Processor¹
15W
2.3 GHz base frequency
2 MB cache, 2 cores, 4 threads
Intel® HD Graphics 610
Supports DDR4 memory up to 2133 MT/s data rate

Standard Features and Configurable Modules

Intel® 7th Generation Celeron® Processors

Intel® Celeron® 3865U Processor¹
15W
1.8 GHz base frequency
2 MB cache, 2 cores, 2 threads
Intel® HD Graphics 610
Supports DDR4 memory up to 2133 MT/s data rate

- 1: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

GRAPHICS

Integrated

Intel® HD Graphics 620
Intel® HD Graphics 610

NOTE: Intel® integrated HD Graphics varies by processor

MEMORY

Type

DDR4-2133 (Transfer rates up to 2133 MT/s)

Maximum

32 GB capacity

Memory Configurations

2 SODIMMs

4 GB (4 GB x 1)

8 GB (4 GB x 2)

8 GB (8 GB x 1)

16 GB (8 GB x 2)

16 GB (16 GB x 1)

32 GB (16 GB x 2)

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system. Memory modules support data transfer rates up to 2133 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.
NOTE: All memory slots are customer accessible / upgradeable.

Standard Features and Configurable Modules

STORAGE AND DRIVES

2.5 inch SATA Hard Disk Drives (HDD)

500GB 7200RPM 2.5in SATA HDD

1TB 7200RPM 2.5in SATA HDD

2.5 inch Solid State Drives (SSD)

128GB 2.5in SATA Three Layer Cell SSD

256GB 2.5in SATA Three Layer Cell SSD

M.2 PCIe NVMe Solid State Drives (SSD)

128GB M.2 2280 PCIe NVMe SSD

256GB M.2 2280 PCIe NVMe SSD

512GB M.2 2280 PCIe NVMe SSD

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

NETWORKING/COMMUNICATIONS

Networking

Realtek RTL8111HSH-CG Gigabit Network Connection

Wireless¹

Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card

Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited.

AUDIO/MULTIMEDIA

HD audio with Conexant CX20632 Codec

Combo Microphone/Headphone Jack

Standard Features and Configurable Modules

KEYBOARDS/POINTING DEVICES/BUTTONS AND FUNCTIONS KEYS

Keyboard

- HP USB Business Slim Standalone Wired Keyboard
- HP USB Conferencing Wired Keyboard
- USB Wired Keyboard

Mouse

- HP Optical Mouse
- USB Hardened Mouse

NOTE: Availability may vary by country

PORTS

Internal slots and Ports

- (1) M.2 PCIe x1 2230 (for WLAN)
- (1) M.2 PCIe x4 2280/2230 Combo (for storage)
- (1) Desktop Mini SATA storage connector

Front I/O Ports

- (2) USB 3.1 Gen 1 ports
- (1) Microphone/Headphone Combo Jack

Rear I/O Ports

- (1) HDMI port
- (1) VGA port
- (1) Serial port
- (2) USB 3.1 Gen 1 ports
- (2) USB 2.0 ports
- RJ45 network connector

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

BAYS

- (1) 2.5" SATA Storage Drive Bay
-

Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Hotkey Support
HP Support Assistant ¹
HP JumpStarts
Buy Office (Sold separately)

Security Management

McAfee LiveSafe™ (1 year subscription) ²

Manageability

HP Cloud Recovery³

1. HP Support Assistant requires Windows and Internet access.

2. Availability may vary by country.

3. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: <https://support.hp.com/us-en/document/c05115630>.

POWER

Power Supply

External 65-watt power adapter

Standard Features and Configurable Modules

WEIGHT AND DIMENSIONS

System

Dimensions	6.97 x 6.89 x 1.35 in (177 x 175 x 34.2 mm)
Weight ¹	2.74 lbs (1.25 kg)
Volume	64 cu in 1.05 L

Packaging dimensions and weight

Dimensions	19.57 x 5.04 x 8.78 in (497 x 128 x 223 mm)
Weight	7.36 lbs (3.34 kg)

Palletization and Container

Type	Air Shipment
Pallet Size	47.24 x 39.37 x 4.96 in 1200 x 1000 x 126 mm
Pallet Profile	1 unit/carton 18 cartons/layer 5 or 6 layers per pallet max depending on details of air freight 90 or 108 units per pallet depending on details of air freight
Pallet Size Loaded	47.24 x 39.37 x 57.64 in 1200 x 1000 x 1464 mm

1. Configured with 1 SATA Drive

Standard Features and Configurable Modules

UNIT ENVIRONMENT AND OPERATING CONDITIONS

Environmental and Industry

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range

Operating: 50° to 95° F (10° to 35° C)¹

Non-operating: -22° to 140° F (-30° to 60° C)

Relative Humidity

Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 0% to 95% (non-condensing at ambient)

Maximum Altitude (unpressurized)

Operating: 10,000 ft (3048 m)

Non-operating: 30,000 ft (9144 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

CERTIFICATIONS

EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See <http://www.epeat.net> for registration status by country¹

WEEE (Waste, Electric and electronic equipment)

ENERGY STAR®

CEL

FCC

UL

RoHS

1. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information..

Standard Features and Configurable Modules

SERVICE AND SUPPORT

On-site Warranty¹: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day² service for parts and labor and complimentary limited technical support³. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack⁴. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.

1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
 3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
 4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.
-

Technical Specifications – Graphics

GRAPHICS

Intel® HD Graphics (integrated)¹

Output Connectors	HDMI, VGA
Maximum Graphics Memory	32GB; however, system memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	32 bits/pixel
Graphics/Video API Support	DirectX 12 OpenGL 4.4

1. All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications – Storage

STORAGE

500GB 7200RPM 2.5in SATA HDD

Capacity	500GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	16 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB 2.5in SATA Three Layer Cell SSD

Drive Weight	<50g
Capacity	128GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 380MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM

Technical Specifications – Storage

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB 2.5in SATA Three Layer Cell SSD

Drive Weight	<62g
Capacity	256GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 450MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 1400MB/s
Maximum Sequential Write	Up to 395MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3



Technical Specifications – Storage

Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD



Technical Specifications – Storage

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Audio

HIGH DEFINITION AUDIO

Type	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	1 Headset connector supporting CTIA style headset
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally
Multi-streaming Capable	Playback multi-streaming allows independent audio streams to be sent to/from the front jacks and integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

Technical Specifications – Power

POWER SUPPLY

Operating Voltage Range	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac
Rated Line Frequency	50Hz~60Hz
Operating Line Frequency	47Hz~63Hz
Rated Input Current	65W \leq 1.7A
Rated Input Current with Energy Efficient* Power Supply	65W \leq 1.7A Average efficiency 88% at 115V Average efficiency 89% at 230V
DC Output	+19.5VV
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power cord length	6.0 ft. (1.83 m)

Technical Specifications – Networking

NETWORKING

Realtek RTL8111HSH-CG Gigabit Network Connection

Connector	RJ-45
System Interface	PCIe + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status

Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Bands	802.11b/g/n	<ul style="list-style-type: none"> 2.402 – 2.482 GHz

Technical Specifications – Networking

		Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
	802.11a/n	<ul style="list-style-type: none"> • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850
Data Rates		<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation		Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security³		<ul style="list-style-type: none"> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI
		¹ Check latest software/driver release for updates on supported security features.
Network Architecture Models		Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming²		IEEE 802.11 compliant roaming between access points
Output Power²		<ul style="list-style-type: none"> • 802.11b : +14dBm minimum • 802.11g : +12dBm minimum • 802.11a : +12dBm minimum • 802.11n HT20(2.4GHz) : +12dBm minimum • 802.11n HT40(2.4GHz) : +12dBm minimum • 802.11n HT20(5GHz) : +10dBm minimum • 802.11n HT40(5GHz) : +10dBm minimum • 802.11ac VHT80(5GHz) : +10dBm minimum
Power Consumption		<ul style="list-style-type: none"> • Transmit mode 2.0 W

Technical Specifications – Networking

	<ul style="list-style-type: none"> • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10 mW • Radio disabled 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1 Mbps : -93.5 dBm maximum • 802.11b, 11 Mbps : -84 dBm maximum • 802.11a/g, 6 Mbps : -86 dBm maximum • 802.11a/g, 54 Mbps : -72 dBm maximum • 802.11n, MCS07 : -67 dBm maximum • 802.11n, MCS15 : -64 dBm maximum • 802.11ac, MCS0 : -84 dBm maximum • 802.11ac, MCS9 : -59 dBm maximum <p><small>³ Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).</small></p>				
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard				
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm				
Weight	Type 2230 : 2.8g				
Operating Voltage	3.3v +/- 9%				
Temperature	<table border="0"> <tr> <td>Operating:</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating:</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </table>	Operating:	14° to 158° F (-10° to 70° C)	Non-operating:	-40° to 176° F (-40° to 80° C)
Operating:	14° to 158° F (-10° to 70° C)				
Non-operating:	-40° to 176° F (-40° to 80° C)				
Humidity	<table border="0"> <tr> <td>Operating:</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating:</td> <td>5% to 95% (non-condensing)</td> </tr> </table>	Operating:	10% to 90% (non-condensing)	Non-operating:	5% to 95% (non-condensing)
Operating:	10% to 90% (non-condensing)				
Non-operating:	5% to 95% (non-condensing)				
Altitude	<table border="0"> <tr> <td>Operating:</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating:</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </table>	Operating:	0 to 10,000 ft (3,048 m)	Non-operating:	0 to 50,000 ft (15,240 m)
Operating:	0 to 10,000 ft (3,048 m)				
Non-operating:	0 to 50,000 ft (15,240 m)				
HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology					
Bluetooth Specification	4.0/4.1/4.2 Compliant				
Frequency Band	2402 to 2480 MHz				
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)				

Technical Specifications – Networking

Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Receiver Sensitivity Legacy	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g

Technical Specifications – Networking

	IEEE 802.11n IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	<ul style="list-style-type: none"> 2.402 – 2.482 GHz <p>NOTE: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.</p>
	802.11a/n	<ul style="list-style-type: none"> 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850
Data Rates	<ul style="list-style-type: none"> 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz) 	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security³	<ul style="list-style-type: none"> IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI 	
	1 Check latest software/driver release for updates on supported security features.	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming²	IEEE 802.11 compliant roaming between access points	

Technical Specifications – Networking

Output Power²	<ul style="list-style-type: none"> • 802.11b : +14dBm minimum • 802.11g : +12dBm minimum • 802.11a : +12dBm minimum • 802.11n HT20(2.4GHz) : +12dBm minimum • 802.11n HT40(2.4GHz) : +12dBm minimum • 802.11n HT20(5GHz) : +10dBm minimum • 802.11n HT40(5GHz) : +10dBm minimum • 802.11ac VHT80(5GHz) : +10dBm minimum 	
Power Consumption	<ul style="list-style-type: none"> • Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW 	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity³	<ul style="list-style-type: none"> • 802.11b, 1Mbps : -93.5dBm maximum • 802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum 	
	<p>3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).</p>	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)

Technical Specifications – Networking

Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
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Technical Specifications – Networking

	<ul style="list-style-type: none">FAX Profile (FAX)Basic Imaging Profile (BIP)2Headset Profile (HSP)Hands Free Profile (HFP)Advanced Audio Distribution Profile (A2DP)
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Technical Specifications – Environmental

ENVIRONMENTAL

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® 2019 registered where applicable. EPEAT registration varies by country. See <http://www.epeat.net> for registration status by country.*
- TCO certified

*Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit <http://www.epeat.net> for more information.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a “Typically Configured Desktop”.

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	4.5350	4.5700	4.3930
Normal Operation (Long idle)	4.0470	4.2030	3.9670
Sleep	0.3880	0.4210	0.3820
Off	0.3500	0.3880	0.3490

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. Search keyword generator on HP’s 3rd party option store for solar generator accessories at www.hp.com/go/options

Heat Dissipation*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	15.4644	15.5837	14.9801
Normal Operation (Long idle)	13.8003	14.3322	13.5275
Sleep	1.3231	1.4356	1.3026
Off	1.1935	1.3231	1.1901

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	3.1	20
Fixed Disk – Random writes	4.4	33

Longevity and Upgrading This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

Technical Specifications – Environmental

Batteries	<p>Spare parts are available throughout the warranty period and or for up to 5 years after the end of production.</p> <p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight</p> <p>Battery size: CR2032 (coin cell) Battery type: Lithium</p>
Additional Information	<ul style="list-style-type: none">• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.• This product contains 0% post-consumer recycled plastic (by wt.)• This product is 95.1% recycle-able when properly disposed of at end of life.
Packaging Materials	<p>External: PAPER/Corrugated</p> <p>Internal: PLASTIC/Expanded Polyethylene - EPE PLASTIC/Polyethylene low density - LDPE</p> <p>The plastic packaging material contains at least 50% recycled content. The corrugated paper packaging materials contains at least 70% recycled content.</p>
Material Usage	<p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none">• Asbestos• Certain Azo Colorants• Certain Brominated Flame Retardants – may not be used as flame retardants in plastics• Cadmium• Chlorinated Hydrocarbons• Chlorinated Paraffins• Formaldehyde• Halogenated Diphenyl Methanes• Lead carbonates and sulfates• Lead and Lead compounds• Mercuric Oxide Batteries• Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.• Ozone Depleting Substances• Polybrominated Biphenyls (PBBs)• Polybrominated Biphenyl Ethers (PBBEs)• Polybrominated Biphenyl Oxides (PBBOs)• Polychlorinated Biphenyl (PCB)• Polychlorinated Terphenyls (PCT)

Technical Specifications – Environmental

- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

For more information about HP's commitment to the environment:

HP Inc. Corporate Environmental Information

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

After-Market Options (availability may vary by region)

Type	Description	Part Number
Display Bracket	HP B300 PC Mounting Bracket	2DW53A
	HP B500 PC Mounting Bracket	2DW52A
	HP Flat Panel Monitor Quick Release	EM870AA
	HP Quick Release Bracket 2	6KD15AA
Desktop Mini Accessories	HP Desktop Mini 500GB HDD/I/O Expansion Module	K9Q82AA
	HP Desktop Mini 65W Power Supply Kit	L2X04AA
	HP Desktop Mini DVD-Writer ODD Expansion Module	K9Q83AA
	HP Desktop Mini G3/G4 Port Cover Kit	1ZE52AA
	HP Desktop Mini I/O Expansion Module	K9Q84AA
	HP Desktop Mini LockBox V2	3EJ57AA
	HP Desktop Mini Security/Dual VESA Sleeve v2	2JA32AA
	HP Desktop Mini Vertical Chassis Stand	G1K23AA
	HP DM VESA Power Supply Holder Kit	1RL87AA
HP G4 Mini 2.5-inch SATA Drive Bay Kit	3TK91AT	
Graphics Options	HP HDMI Standard Cable Kit	T6F94AA
Security Hardware	HP Dual Head Keyed Cable Lock	T1A64AA
	HP Keyed Cable Lock 10mm	T1A62AA
Data Storage Drives	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	Intel Optane 118GB M.2 SSD	4RV34AA
	Intel Optane Memory 16GB	1WV97AA
	HP 256GB SATA TLC Non-SED Solid State Drive	P1N68AA
Input Devices	HP Conferencing Keyboard	K8P74AA
	HP USB Business Slim Keyboard	N3R87AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP USB Hardened Mouse	P1N77AA
	HP USB Mouse	QY777AA
Adapter	HP USB to Serial Port Adapter	J7B60AA
System Memory	HP 4GB DDR4-2666 SODIMM	3TK86AA
	HP 8GB DDR4-2666 SODIMM	3TK88AA
	HP 16GB DDR4-2666 SODIMM	3TK84AA
Multimedia Devices	HP Business Headset v2	T4E61AA
	HP USB Business Speakers v2	N3R89AA

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Change Log

Date of change:	Version History:		Description of change:
July 13, 2018	From v1 to v2	Update	EPEAT Gold updated to EPEAT Silver/Back image on call outs updated
February 5, 2019	From v2 to v3	Update	HP PhoneWise, HP ePrinter + Jet advantage and HP Velocity removed
June 17, 2019	From v3 to v4	Update	EPEAT references updated 512GB M.2 added to Storage section Environmental section bullet overset corrected
June 20, 2019	From v4 to v5	Update	Hp Cloud recovery and its disclaimer added to software section
August 16, 2019	From v5 to v6	Update	Cable lock slot upgraded to Standard
November 12, 2019	From v6 to v7	Update	EPEAT references updated